AMENDMENTS TO THE CLAIMS

Please amend claims 1, 3, 5 and 10, 14 and 16, cancel claims 2, 6-8 and 17-19 without prejudice or disclaimer, and add new claims 20-21 as follows.

1. (Currently Amended) A method of supplying a developing solution to a surface of a substrate to perform developing treatment for the substrate, comprising:

a first step of supplying the developing solution to the surface of the substrate while a developing solution supply nozzle is moving relative to the substrate; and

a second step of developing the substrate for a first predetermined period of time, said second step having the step of developing the substrate in stationary condition while stopping the substrate for a second predetermined period of time after the completion of said first step, the step of making a concentration of the developing solution on the substrate uniform by stirring the developing solution on the surface of the substrate after a the second predetermined period of time, wherein said stirring step is performed by rotating the substrate; the step of thereafter further developing the substrate in stationary condition while stopping the substrate for a third predetermined period of time, and the step of washing the substrate while rotating the substrate after the third predetermined period of time; the step of measuring a thickness of the developing solution after said step of stirring the developing solution; and

the step of changing at least one of a rotation time of the substrate based on the thickness measurement, a rotation speed of the substrate based on the thickness measurement, and a rotation acceleration of the substrate based on the thickness measurement.

2. (cancelled)

3. (Currently amended) A method as set forth in claim [[2]]1, wherein said stirring step by rotation is performed by normally rotating the substrate and then reversely rotating the substrate.

4. (Original) A method as set forth in claim 3, wherein the reverse rotation is performed at a speed higher than a rotation speed in the

normal rotation.

5. (Currently amended) A method as set forth in claim [[2]]1,

wherein the substrate is rotated so that a thickness of the developing solution after said step of stirring the developing solution is not less than a predetermined thickness.

6. (cancelled)

7. (cancelled)

8. (cancelled)

9. (Previously presented) A method as set forth in claim 1,

wherein the developing solution supply nozzle supplies the developing solution to the substrate while moving from a first end to a second end of the substrate in said first step.

10. (Currently Amended) A method as set forth in claim [[2]]1,

wherein the developing solution supply nozzle supplies the developing solution to the substrate while moving from a first end to a second end of the substrate in said first step.

11. (Previously presented) A method as set forth in claim 9, further comprising the step of:

supplying the developing solution again to the surface of the substrate while moving the developing solution supply nozzle from the second end to the first end of the substrate after said stirring step.

12. (Previously presented) A method as set forth in claim 10, further comprising the step of:

supplying the developing solution again to the surface of the substrate while moving the developing solution supply nozzle from the second end to the first end of the substrate after the stirring step.

13. (Original) A method as set forth in claim 1,

wherein the developing solution is supplied to the substrate while the developing solution supply nozzle is stopped above the substrate and the substrate is rotated in said first step.

14. (Currently amended) A method as set forth in claim 13, further comprising the step of:

supplying the developing solution again to the substrate after said stirring step while the developing solution supply nozzle is stopped above the substrate and the substrate is rotated in a direction opposite to the above-rotation direction in which the substrate is rotated after said stirring stepin said first step.

15. (Original) A method as set forth in claim 1,

wherein the developing solution is supplied to the substrate while the developing solution supply nozzle is stopped or moving above the substrate with the substrate being rotated in said first step.

16. (Currently amended) A method as set forth in claim 15, further comprising the step of:

supplying the developing solution again to the substrate after said stirring step while the developing solution supply nozzle is stopped or moving above the substrate with the substrate being rotated in a direction opposite to the above-rotation direction in which the substrate is rotated after said stirring stepin said first step.

17-19 (canceled)

20. (New) A method of supplying a developing solution to a surface of a substrate to perform developing treatment for the substrate, comprising:

a first step of supplying the developing solution to the surface of the substrate while a developing solution supply nozzle is moving relative to the substrate; and

a second step of developing the substrate for a first predetermined period of time,

said second step having the step of developing the substrate in the stationary condition while stopping the substrate for a second predetermined period of time after the completion of

said first step, the step of making a concentration of the developing solution on the substrate uniform by stirring the developing solution on the surface of the substrate after the second predetermined period of time, the step of thereafter further developing the substrate in stationary condition while stopping the substrate for a third predetermined period of time, the step of washing the substrate while rotating the substrate after the third predetermined period of time,

said second step of predetermined period of time being a period of time 50% to 80% of progress of the chemical reaction of developing.

21. (New) A method as set forth in claim 20,

wherein the nozzle moves parallel to the substrate in one direction in said first step.